

Silicon Carbide Power Mosfet

1. Product Information

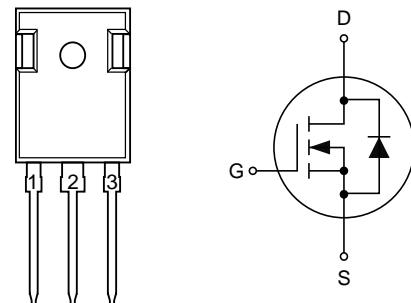
Features

- 1200V, 40mΩ, 79A
- High Blocking Voltage with Low On-Resistance
- Fast switching speed with low capacitances
- Easy to Parallel and Simple to Drive
- Resistant to Latch-Up
- Halogen-free, RoHS compliant

Pin Description

Pin	Description
1	Gate(G)
2	Drain(D)
3	Source(S)

Simplified Outline Symbol



Top View
TO-247-3L

Applications

- Power Factor Correction or DC/DC Converters
- Solar Inverters
- EV Charging Station
- Motor Drives
- Switch Mode Power Supply

Package Marking and Ordering Information

Product Name	Package	Marking	Form	Quantity (PCS)
KJC12040P	TO-247-3L	KJC12040P	Tube	30

2. Absolute Maximum Ratings (T_C=25°C unless otherwise noted)

Symbol	Parameter	Values	Unit
V _{DS}	Drain-Source Voltage	1200	V
V _{GS}	Gate-Source Voltage (Absolute maximum values)	-10/+22	V
V _{GS}	Gate-Source Voltage (Recommended operational values)	-5/+18	V
I _D	Continuous Drain Current, V _{GS} =18V, T _C =25°C	79	A
I _D	Continuous Drain Current, V _{GS} =18V, T _A =100°C	50	A
I _{DM}	Pulsed Drain Current, Pulse width t _p limited by T _{jmax}	180	A
P _D	Power Dissipation, T _C =25°C, T _J =150°C	357	W
T _J , T _{STG}	Operating Junction and Storage Temperature	-55~150	°C
R _{θJC}	Thermal Resistance-Junction to Case	0.47	°C/W

3. Electrical Characteristics ($T_C=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Type	Max	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=100\mu\text{A}$	1200	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=1200\text{V}, V_{\text{GS}}=0\text{V}$	-	1	100	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=18\text{V}, V_{\text{DS}}=0\text{V}$	-	-	250	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=10\text{mA}$	2.0	2.9	4.0	V
		$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=10\text{mA}, T_J=150^\circ\text{C}$	-	2.1	-	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=18\text{V}, I_{\text{D}}=40\text{A}, T_J=25^\circ\text{C}$	-	43	53	$\text{m}\Omega$
		$V_{\text{GS}}=18\text{V}, I_{\text{D}}=40\text{A}, T_J=150^\circ\text{C}$	-	57	-	$\text{m}\Omega$
G_{FS}	Transconductance	$V_{\text{GS}}=20\text{V}, I_{\text{D}}=40\text{A}, T_J=25^\circ\text{C}$	-	21.2	-	S
		$V_{\text{GS}}=20\text{V}, I_{\text{D}}=40\text{A}, T_J=150^\circ\text{C}$	-	20.4	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=1000\text{V}, V_{\text{GS}}=0\text{V}, F=100\text{kHz}, V_{\text{AC}}=25\text{mV}$	-	3360	-	pF
C_{oss}	Output Capacitance		-	140	-	pF
C_{rss}	Reverse Transfer Capacitance		-	12	-	pF
E_{oss}	C_{oss} Stored Energy		-	138	-	μJ
Q_g	Total Gate Charge	$V_{\text{DD}}=800\text{V}, I_{\text{D}}=40\text{A}, V_{\text{GS}}=-5/+18\text{V}$	-	136	-	nC
Q_{gs}	Gate-Source Charge		-	47	-	nC
Q_{gd}	Gate-Drain Charge		-	39	-	nC
Switching Characteristics						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=800\text{V}, I_{\text{D}}=40\text{A}, V_{\text{GS}}=-5/+18\text{V}, R_{\text{G}}=2.5\Omega, L=150\mu\text{H}, T_J=25^\circ\text{C}$ Timing relative to V_{DS}	-	18	-	ns
t_r	Turn-on Rise Time		-	67	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	22	-	ns
t_f	Turn-off Fall Time		-	13	-	ns
E_{on}	Turn-on Energy		-	2	-	mJ
E_{off}	Turn-off Fall Time Energy		-	0.3	-	mJ
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=-5\text{V}, I_{\text{s}}=20\text{A}, T_J=25^\circ\text{C}$	-	5.1	-	V
		$V_{\text{GS}}=-5\text{V}, I_{\text{s}}=20\text{A}, T_J=150^\circ\text{C}$	-	4.7	-	V
I_{s}	Continuous Diode Forward Current	$V_{\text{GS}}=-5\text{V}, T_c=25^\circ\text{C}$	-	-	58	A
I_{SM}	Maximum Pulsed Diode Forward Current	$V_{\text{GS}}=-5\text{V}, \text{Pulse width } t_p \text{ limited by } T_{j\text{max}}$	-	-	180	A
I_{rrm}	Peak Reverse Recovery Current	$V_{\text{GS}}=-5\text{V}, I_{\text{SD}}=40\text{A}, V_{\text{R}}=800\text{V}, dI/dt=1210\text{A}/\mu\text{s}, T_J=25^\circ\text{C}$	-	20	-	A
T_{rr}	Reverse Recovery Time		-	52	-	ns
Q_{rr}	Reverse Recovery Charge		-	380	-	nC

4. Typical Characteristics

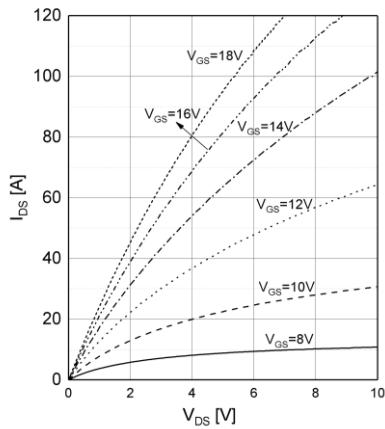


Figure 1. Output Characteristics

$I_{DS}=f(V_{DS})$, $T_J=25^\circ\text{C}$

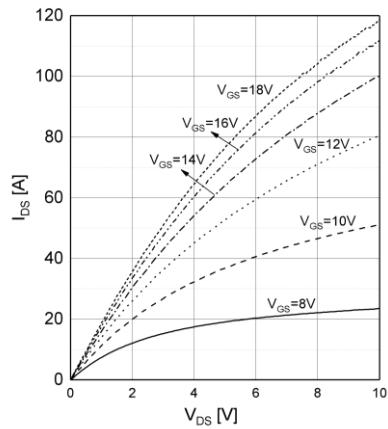


Figure 2. Output Characteristics

$I_{DS}=f(V_{DS})$, $T_J=150^\circ\text{C}$

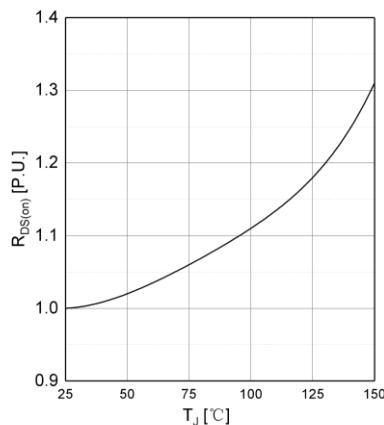


Figure 3. Output Characteristics

$R_{DS(\text{on})}=f(T_J)$, $I_{DS}=40\text{A}$, $V_{GS}=18\text{V}$

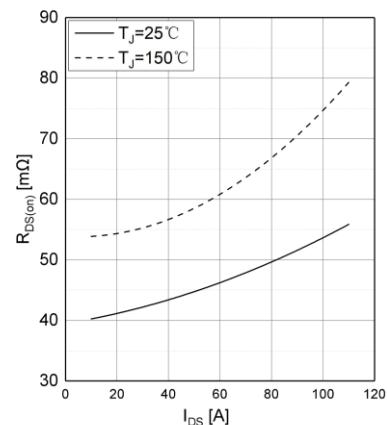


Figure 4. On-Resistance

$R_{DS(\text{on})}=f(I_{DS})$, $V_{GS}=18\text{V}$

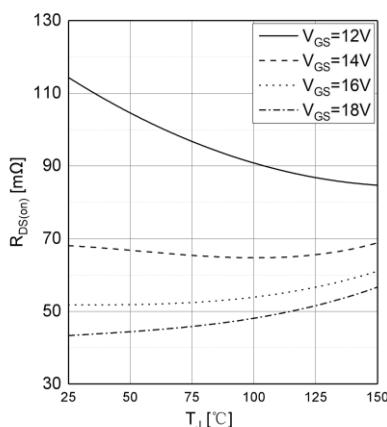


Figure 5. On-Resistance

$R_{DS(\text{on})}=f(T_J)$, $I_{DS}=40\text{A}$

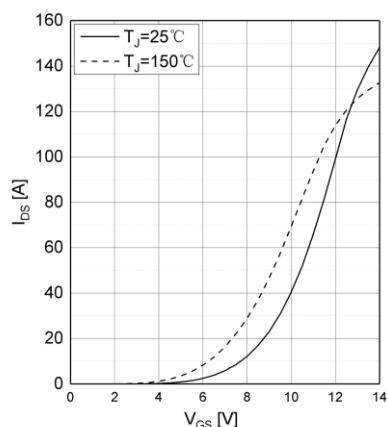


Figure 6. Transfer Characteristics

$I_{DS}=f(V_{GS})$, $V_{DS}=20\text{V}$

4. Typical Characteristics(cont.)

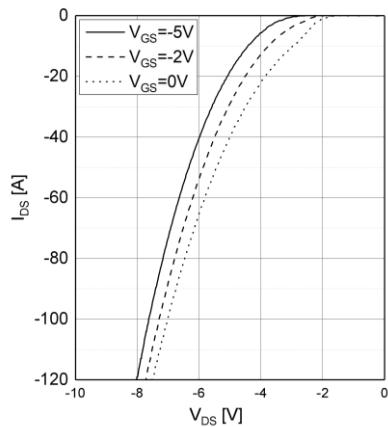


Figure 7. Body Diode Characteristics

$I_{DS}=f(V_{DS})$, $T_J=25^\circ\text{C}$

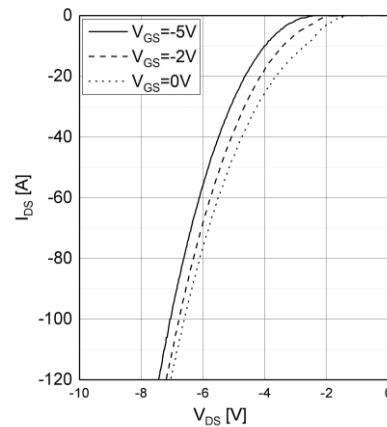


Figure 8. Body Diode Characteristics

$I_{DS}=f(V_{DS})$, $T_J=150^\circ\text{C}$

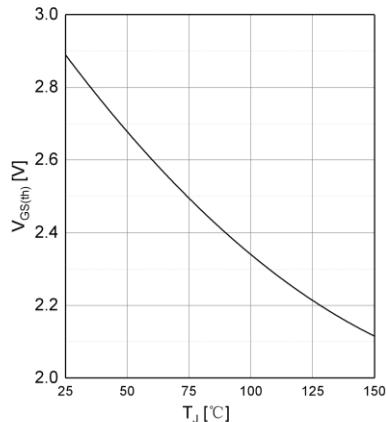


Figure 9. Threshold Voltage

$V_{GS(th)}=f(T_J)$, $V_{GS}=V_{DS}$, $I_{DS}=10\text{mA}$

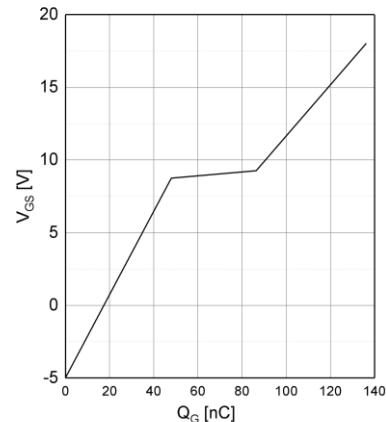


Figure 10. Gate Charge Characteristics

$V_{GS}=f(Q_G)$, $I_{DS}=40\text{A}$, $I_{GS}=50\text{mA}$, $V_{DS}=800\text{V}$,
 $T_J=25^\circ\text{C}$

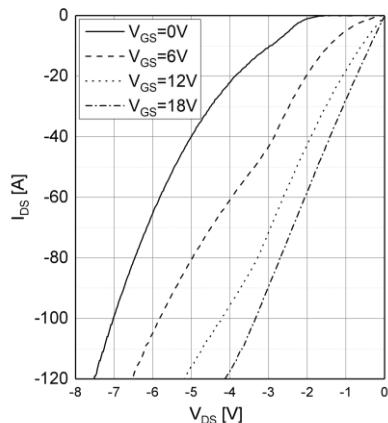


Figure 11. 3rd Quadrant Characteristics

$I_{DS}=f(V_{DS})$, $T_J=25^\circ\text{C}$

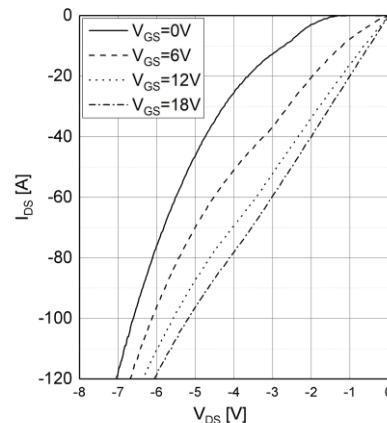


Figure 12. 3rd Quadrant Characteristics

$I_{DS}=f(V_{DS})$, $T_J=150^\circ\text{C}$

4. Typical Characteristics(cont.)

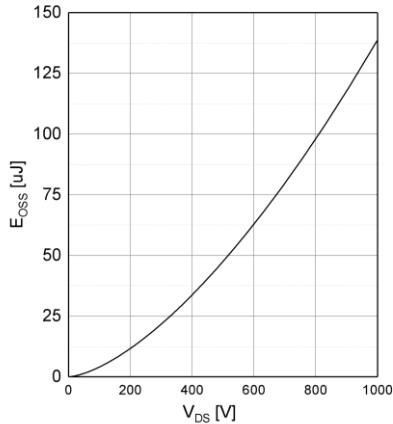


Figure 13. Output Capacitor Stored Energy
 $E_{OSS}=f(V_{DS})$

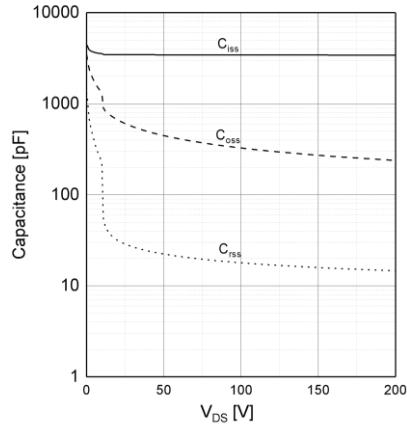


Figure 14. Capacitances
 Capacitances=f(V_{DS}), $T_J=25^\circ\text{C}$, $V_{AC}=25\text{mV}$,
 $f=100\text{kHz}$, (0-200V)

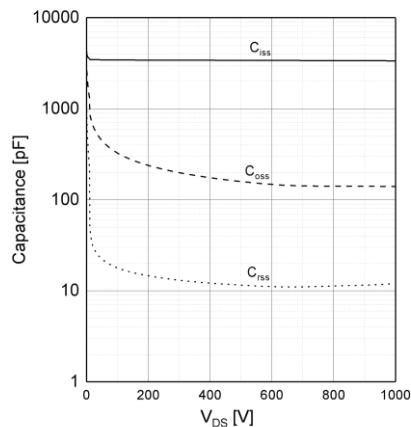


Figure 15. Capacitances
 Capacitances=f(V_{DS}), $T_J=25^\circ\text{C}$, $V_{AC}=25\text{mV}$,
 $f=100\text{kHz}$, (0-1000V)

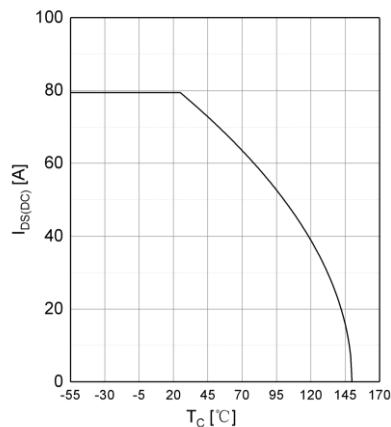


Figure 16. Continuous Drain Current Derating
 $I_{DS(DC)}=f(T_C)$, $T_J \leq 150^\circ\text{C}$

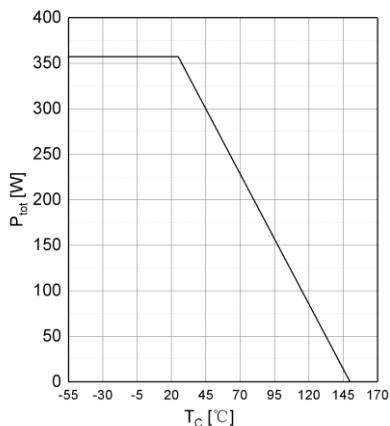


Figure 17. Maximum Power Dissipation Derating
 $P_{tot}=f(T_C)$, $T_J \leq 150^\circ\text{C}$

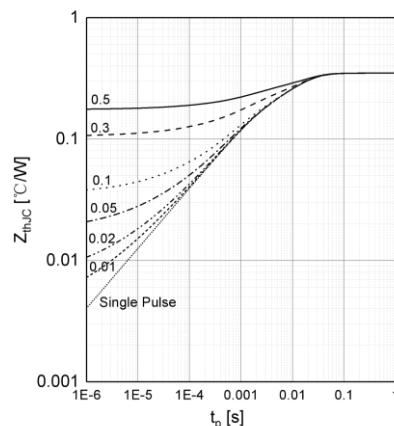


Figure 18. Transient Thermal Impedance (Junction-Case)
 $Z_{thJC}=f(t_p)$

4. Typical Characteristics(cont.)

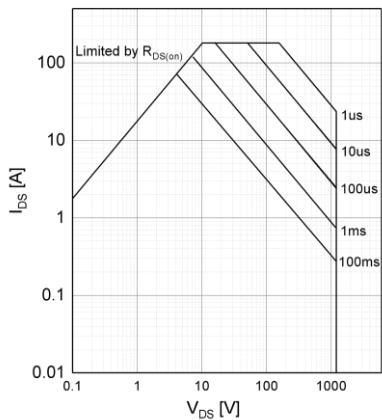


Figure 19. Safe Operating Area

$I_{DS}=f(V_{DS})$, $T_c=25^\circ C$, $D=0$, Parameter: t_p

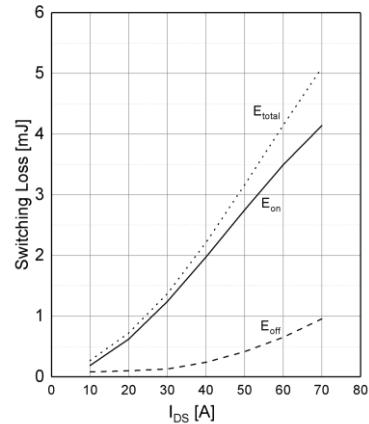


Figure 20. Switching Energy

Switching Loss=f(I_{DS}), $T_J=25^\circ C$, $V_{DD}=800V$,
 $R_{G(ext)}=2.5\Omega$, $V_{GS}=-5V/+18V$, $L=150\mu H$

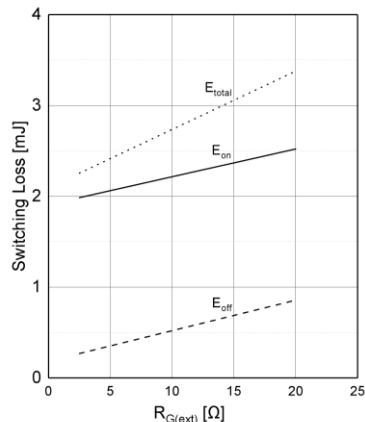


Figure 21. Switching Energy

Switching Loss=f($R_{G(ext)}$), $T_J=25^\circ C$,
 $V_{DD}=800V$, $I_{DS}=40A$, $V_{GS}=-5V/+18V$, $L=150\mu H$

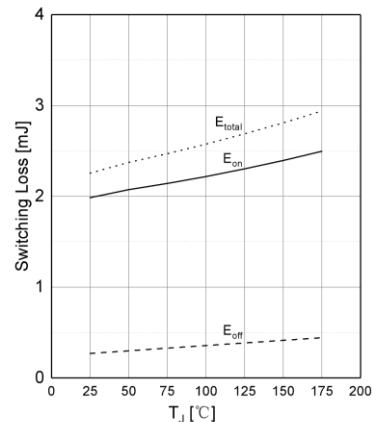


Figure 22. Switching Energy

Switching Loss=f(T_J), $V_{DD}=800V$, $I_{DS}=40A$,
 $R_{G(ext)}=2.5\Omega$, $V_{GS}=-5V/+18V$, $L=150\mu H$

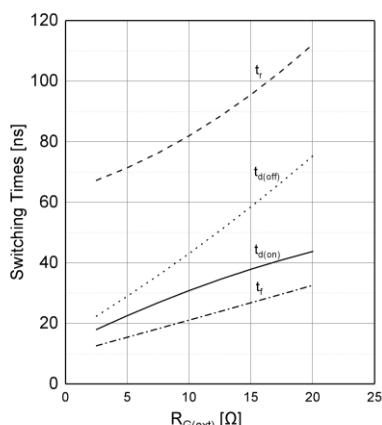


Figure 23. Switching Times

Switching Times=f($R_{G(ext)}$), $T_J=25^\circ C$,
 $V_{DD}=800V$, $I_{DS}=40A$, $V_{GS}=-5V/+18V$, $L=150\mu H$

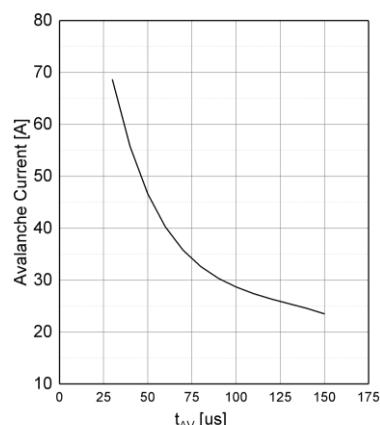
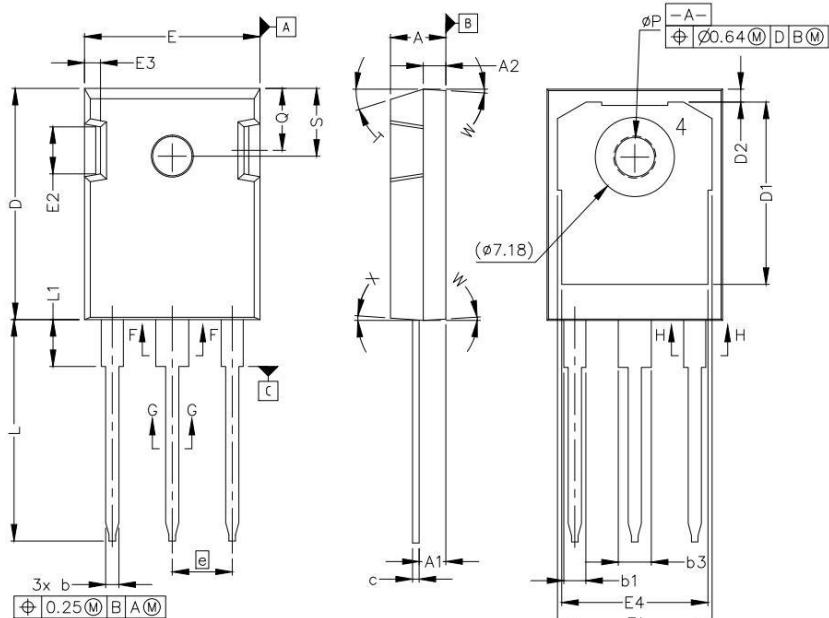


Figure 24. Single Avalanche Safe Operating Area

Avalanche Current=f(t_{AV}),
 $T_J=25^\circ C$, $V_{DD}=50V$

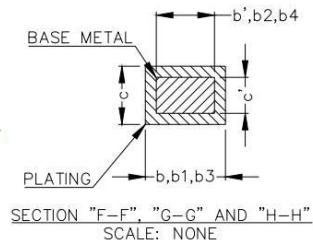
5. Package Mechanical Data

TO-247-3L Package



NOTE :
 1. ALL METAL SURFACES: TIN PLATED, EXCEPT AREA OF CUT
 2. DIMENSIONS & TOLERANCES CONFIRM TO
 ASME Y14.5M-1994
 3. ALL DIMENSIONS ARE IN MILLIMETERS.
 ANGLES ARE IN DEGREES.
 4. THIS DRAWING WILL MEET ALL DIMENSIONS REQUIREMENT
 OF JEDEC outlines TO-247 AD.

- 1 - GATE
 2 - DRAIN (COLLECTOR)
 3 - SOURCE (EMITTER)
 4 - DRAIN (COLLECTOR)



Symbol	MIN	MAX
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b'	1.07	1.28
b	1.07	1.33
b1	1.91	2.41
b2	1.91	2.16
b3	2.87	3.38
b4	2.87	3.13
c'	0.55	0.65
c	0.55	0.68
D	20.80	21.10
D1	16.25	17.65
D2	0.95	1.25
E	15.75	16.13
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e	5.44 BSC	
N	3	
L	19.81	20.32
L1	4.10	4.40
ϕP	3.51	3.65
Q	5.49	6.00
S	6.04	6.30
T	17.5° REF.	
W	3.5° REF.	
X	4° REF.	